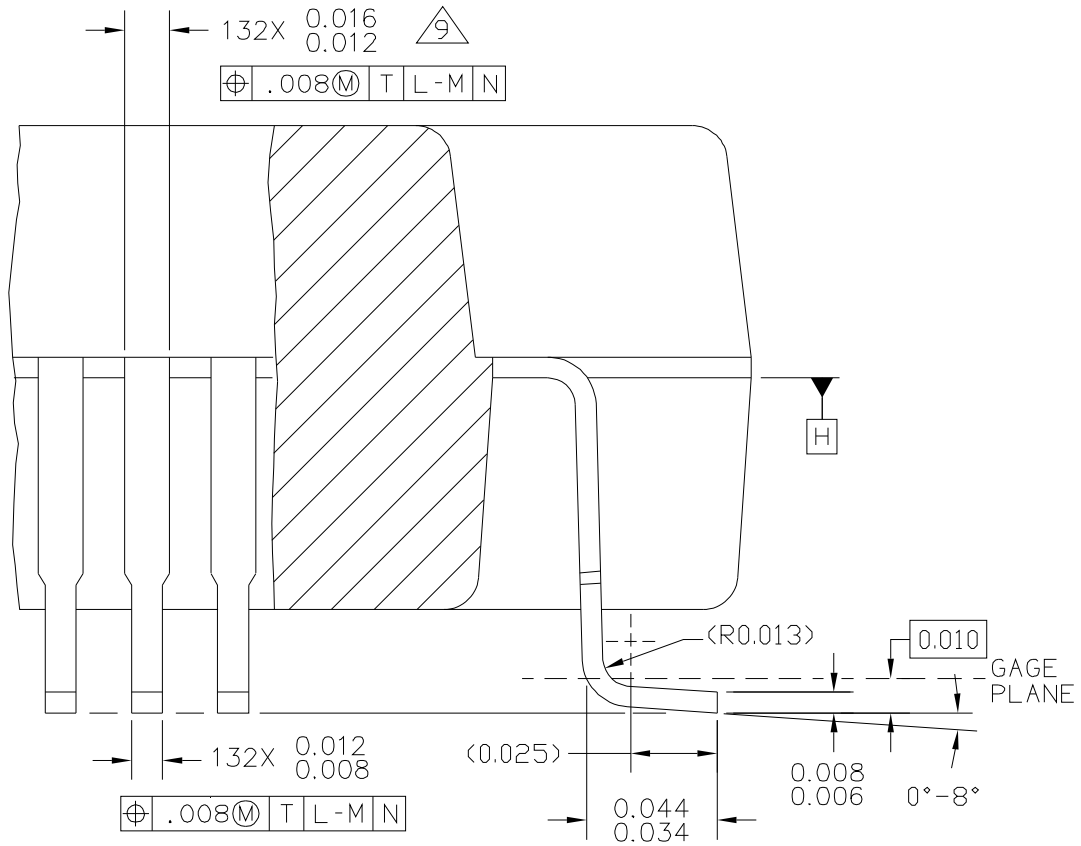
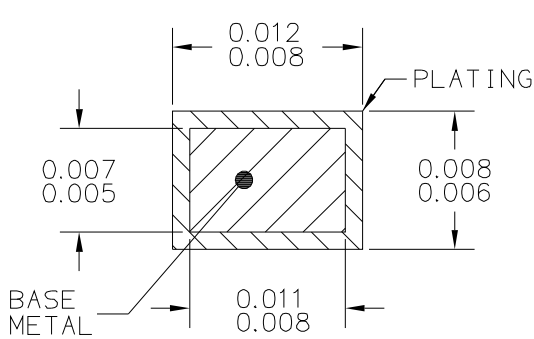


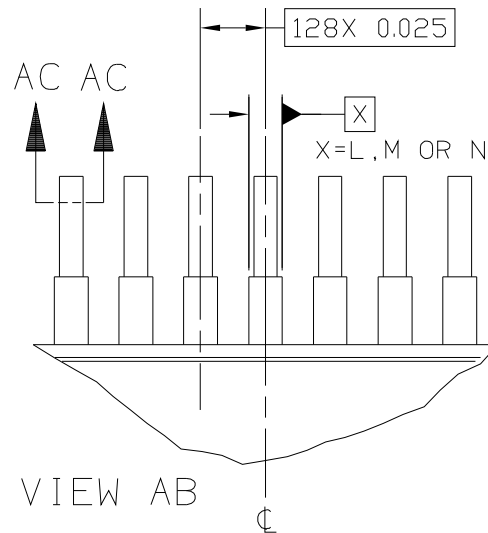
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SECTION AA-AA



SECTION AC-AC



VIEW AB

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	STANDARD: NON-JEDEC	
	SOT1695-1	29 JAN 2016



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5-1994.

2. DIMENSIONS IN INCHES.

3. DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION FOR THE DIMENSIONS IS .007.

4. DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION FOR THE DIMENSIONS IS .010.

5. DATUM PLANE H IS LOCATED AT THE UNDERSIDE OF LEADS WHERE LEADS EXIT PACKAGE BODY.

6. DATUMS L, M AND N TO BE DETERMINED WHERE CENTER LEADS EXIT PACKAGE BODY AT DATUM H.

7. DIMENSIONS TO BE DETERMINED AT SEATING PLANE, DATUM T.

8. DIMENSIONS TO BE DETERMINED AT DATUM PLANE H.

9. DIMENSION DOES NOT INCLUDE DAM BAR PROTRUSIONS. DAM BAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED .019.

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